

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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### Title of Invention

ENDPOINT DETECTION IN CHEMICAL-MECHANICAL  
POLISHING OF PATTERNED WAFERS HAVING A LOW PATTERN  
DENSITY

Application Number : 10/707120  
Confirmation Number:  
First Named Applicant: Xinhui Wang  
Attorney Docket Number: FIS920030031  
Art Unit: 3723  
Examiner:  
Search string: ( 6176765 or 6291351 or 6440263 ).pn

### US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

| init | Cite.No. | Patent No. | Date       | Patentee  | Kind | Class | Subclass |
|------|----------|------------|------------|-----------|------|-------|----------|
| DVN  | 1        | 6176765    | 2001-01-23 | Li et al. |      | —     | —        |
| ↓    | 2        | 6291351    | 2001-09-18 | Li et al. |      | —     | —        |
| ↓    | 3        | 6440263    | 2002-08-27 | Li et al. |      | —     | —        |

### Signature

| Examiner Name          | Date     |
|------------------------|----------|
| <i>Sung van Nguyen</i> | 8-9-2004 |